Electronic Patent Application Fee Transmittal								
Application Number:	10549440							
Filing Date:	16-Sep-2005							
Title of Invention:	Copper alloy sputtering target process for producing the same and semiconductor element wiring							
First Named Inventor/Applicant Name:	Takeo Okabe							
Filer:	William Bak							
Attorney Docket Number:	OGOSH39USA							
Filed as Large Entity								
U.S. National Stage under 35 USC 371 Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Submission- Information Disclosure Stmt	1806	1	180	180
	Tot	180		